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FEATURES

- Versatile digital voltage mode controller
- High speed input voltage feedforward control
- 6 pulse-width modulation (PWM) logic outputs with 625 ps resolution
- Switching frequency: 49 kHz to 625 kHz
- Frequency synchronization as master and slave device
- Multiple energy saving modes
- Adaptive dead time compensation for efficiency optimization
- Low device power consumption: 100 mW typical
- Direct parallel control for power supplies without OR'ing devices
 - Accurate droop current share
 - Pre-bias startup
 - Reverse current protection
 - Conditional overvoltage protection
- Extensive fault detection and protection
- PMBus compliant
- Graphical user interface (GUI) for ease of programming
- On-board EEPROM for programming and data storage
- Available in a 24-lead, 4 mm × 4 mm LFCSP
- 40°C to +125°C operating temperature

APPLICATIONS

- High density isolated dc-to-dc power supplies
 - Intermediate bus converters
 - High availability parallel power systems
- Server, storage, industrial, networking, and communications infrastructure

GENERAL DESCRIPTION

The **ADP1051** is an advanced digital controller with a PMBus™ interface targeting high density, high efficiency dc-to-dc power conversion. This controller implements voltage mode control with high speed, input line feedforward for enhanced transient and improved noise performance. The **ADP1051** has six programmable pulse-width modulation (PWM) outputs capable of controlling most high efficiency power supply topologies, with added control of synchronous rectification (SR). The device includes adaptive dead time compensation to improve efficiency over the load range, and programmable light load mode operation, combined with low power consumption, to reduce system standby power losses.

The **ADP1051** implements several features to enable a robust system of parallel and redundant operation for customers that require high availability or parallel connection. The device provides synchronization, reverse current protection, pre-bias startup, accurate current sharing between power supplies, and conditional overvoltage techniques to identify and safely shut down an erroneous power supply in parallel operation mode.

The **ADP1051** is based on flexible state machine architecture and is programmed using an intuitive GUI. The easy to use interface reduces design cycle time and results in a robust, hardware coded system loaded into the built-in EEPROM. The small size (4 mm × 4 mm) LFCSP package makes the **ADP1051** ideal for ultracompact, isolated dc-to-dc power module or embedded power designs.

TYPICAL APPLICATIONS CIRCUIT

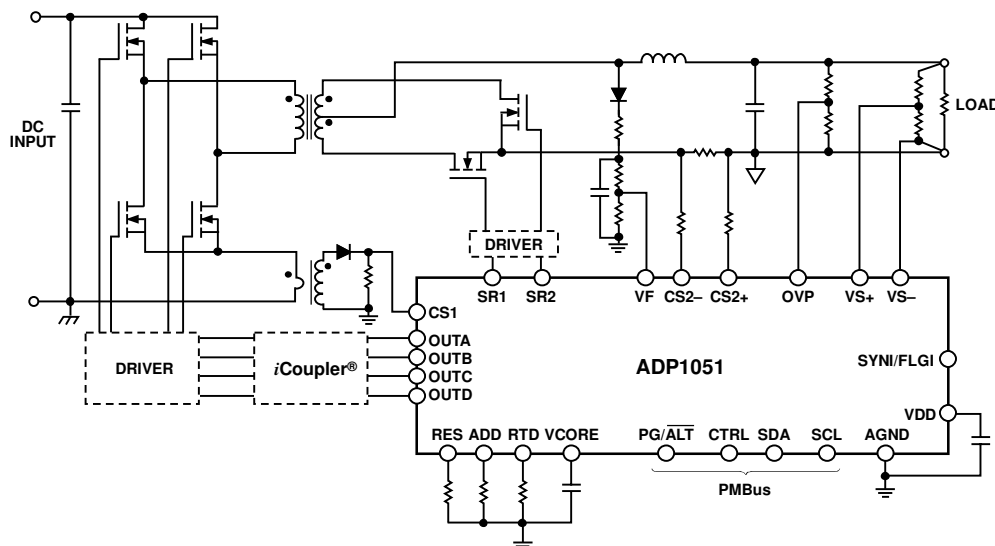


Figure 1.

Rev. A

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COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- ADP1051 Evaluation Board

DOCUMENTATION

Application Notes

- AN-1306: ADP1050 and ADP1051 EEPROM Programming and Calibration in the Power Supply Manufacturing Environment

Data Sheet

- ADP1051: Digital Controller for Isolated Power Supply with PMBus Interface Data Sheet

User Guides

- UG-566: 240 W Evaluation Board Kit for the ADP1051, Digital Controller for Isolated Power Supply with PMBus Interface

SOFTWARE AND SYSTEMS REQUIREMENTS

- ADP1050/ADP1051/ADP1052 Software

REFERENCE MATERIALS

Press

- Analog Devices' Next Generation of Digital Power Controllers with PMBus Interface Targets Highest Density, Energy Efficient Isolated Power Converters

Technical Articles

- Designing Digital Power Supplies With A State Machine

DESIGN RESOURCES

- ADP1051 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all ADP1051 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

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6/14—Rev. 0 to Rev. A

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7/13—Revision 0: Initial Version

SPECIFICATIONS

$V_{DD} = 3.0\text{ V to }3.6\text{ V}$, $T_J = -40^\circ\text{C to }+125^\circ\text{C}$, unless otherwise noted. FSR = full-scale range.

Table 1.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
SUPPLY						
Supply Voltage	V_{DD}	3.0	3.3	3.6	V	2.2 μF capacitor connected to AGND
Supply Current	I_{DD}		28.5	33	mA	Normal operation; PWM pins unloaded
			$I_{DD} + 6$		mA	During EEPROM programming
			50	100	μA	Shutdown; V_{DD} below undervoltage lockout (UVLO)
POWER-ON RESET						
Power-On Reset				3.0	V	V_{DD} rising
UVLO Threshold		2.75	2.85	2.97	V	V_{DD} falling
UVLO Hysteresis			35		mV	
OVLO Threshold		3.7	3.9	4.1	V	
OVLO Debounce			2		μs	VDD_OV flag debounce set to 2 μs
			500		μs	VDD_OV flag debounce set to 500 μs
VCORE PIN						
Output Voltage	V_{CORE}	2.45	2.6	2.75	V	330 nF capacitor connected to AGND
OSCILLATOR AND PLL						
PLL Frequency		190	200	210	MHz	RES input = 10 k Ω ($\pm 0.1\%$)
Digital PWM Resolution			625		ps	
OUTA, OUTB, OUTC, OUTD, SR1, SR2 PINS						
Output Low Voltage	V_{OL}			0.4	V	$I_{OH} = +10\text{ mA}$
Output High Voltage	V_{OH}	$V_{DD} - 0.4$			V	$I_{OL} = -10\text{ mA}$
Rise Time	t_R		3.5		ns	$C_{LOAD} = 50\text{ pF}$
Fall Time	t_F		1.5		ns	$C_{LOAD} = 50\text{ pF}$
Output Source Current	I_{OL}	-10			mA	
Output Sink Current	I_{OH}			10	mA	
Synchronization Signal Output (SYNO) Positive Pulse Width		600	640	680	ns	OUTC or OUTD programmed as SYNO
VS+, VS- VOLTAGE SENSE PINS						
Input Voltage Range	V_{IN}	0	1	1.6	V	Differential voltage from VS+ to VS-
Leakage Current				1.0	μA	
VS Accurate ADC						
Valid Input Voltage Range		0		1.6	V	
ADC Clock Frequency			1.56		MHz	
Register Update Rate			10		ms	
Measurement Resolution			12		Bits	
Measurement Accuracy						Factory trimmed at 1.0 V
		-5		+5	% FSR	0% to 100% of input voltage range
		-80		+80	mV	
		-2		+2	% FSR	10% to 90% of input voltage range
		-32		+32	mV	
		-1.0		+1.0	% FSR	900 mV to 1.1 V
		-16		+16	mV	
Temperature Coefficient				70	ppm/ $^\circ\text{C}$	
Voltage Differential from VS- to AGND		-200		+200	mV	
VS High Speed ADC						
Equivalent Sampling Frequency	f_{SAMP}		f_{SW}		kHz	
Equivalent Resolution			6		Bits	$f_{SW} = 390.5\text{ kHz}$
Dynamic Range			± 25		mV	Regulation voltage = 0 mV to 1.6 V

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
VS UVP Digital Comparator Threshold Accuracy Comparator Update Speed		-2	82	+2	% FSR μ s	Triggers VOUT_UV_FAULT flag 10% to 90% of input voltage range
OVP PIN Leakage Current OVP Comparator Voltage Range Threshold Accuracy Propagation Delay (Latency)				1.0 1.5 +1.6 61 85	μ A V % ns	Triggers VOUT_OV_FAULT flag Differential voltage from OVP to VS- 0.75 V to 1.5 V voltage range Debounce time not included
VF VOLTAGE SENSE PIN Input Voltage Range Leakage Current General ADC Valid Input Voltage Range ADC Clock Frequency Register Update Rate Measurement Resolution Measurement Accuracy VF UVP Digital Comparator Threshold Accuracy Comparator Update Speed Feedforward ADC Input Voltage Range Resolution Sampling Period	V _{IN}	0 0 -2 -32 -5 -80	1 1.56 1.31 11	1.6 1.0 1.6 +2 +32 +5 +80	V μ A V MHz ms Bits % FSR mV % FSR mV	Voltage from VF to AGND 10% to 90% of input voltage range 0% to 100% of input voltage range Triggers VIN_LOW or VIN_UV_FAULT flag Based on VF general ADC parameter values ms
CS1 CURRENT SENSE PIN Input Voltage Range Source Current CS1 ADC Valid Input Voltage Range ADC Clock Frequency Register Update Rate Measurement Resolution Measurement Accuracy CS1 OCP Comparator Reference Accuracy Propagation Delay (Latency) CS3 ¹ Measurement and Digital Comparator Register Update Rate Comparator Speed	V _{IN}	0 -1.2 0 -2 -32 -5 -80 1.185 0.235	1 10 12	1.6 -0.35 1.6 +2 +32 +5 +80 1.2 0.265 65 10 10	V μ A V MHz ms Bits % FSR mV % FSR mV V V ns ms ms	Voltage from CS1 to AGND 10% to 90% of input voltage range 0% to 100% of input voltage range Triggers internal CS1_OCP flag When set to 1.2 V When set to 0.25 V Debounce/blanking time not included Triggers CS3_OC_FAULT flag

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
CS2+, CS2– CURRENT SENSE PINS						
Input Voltage Range	V _{IN}	0		120	mV	Differential voltage from CS2+ to CS2–
Common-Mode Voltage at CS2+ and CS2–		0.8	1.15	1.4	V	To achieve CS2 measurement accuracy
Current Sink (High Side)		1.87	1.915	1.96	mA	
Current Source (Low Side)		195	225	255	μA	
Temperature Coefficient					95	ppm/°C
CS2 ADC						
Valid Input Voltage Range		0		120	mV	
ADC Clock Frequency			1.56		MHz	
Measurement Resolution			12		Bits	
Low-Side Mode Current Measurement Sense Accuracy						4.99 kΩ (0.01%) level shift resistors
		–1.9		+1.9	% FSR	From 0 mV to 110 mV
		–2.28		+2.28	mV	
		–6.1		+1.4	% FSR	From 110 mV to 120 mV
		–7.32		+1.68	mV	
High-Side Mode Current Measurement Sense Accuracy						CS2 high-side factory trim values loaded; 4.99 kΩ (0.01%) level shift resistors; V _{OUT} = 11 V
		–1.6		+2.3	% FSR	From 0 mV to 110 mV
		–1.92		+2.76	mV	
		–5.3		+0.7	% FSR	From 110 mV to 120 mV
		–6.36		+0.84	mV	
CS2 OCP Digital Comparator Threshold Accuracy						Triggers IOUT_OC_FAULT flag Same as CS2 ADC low-side and high-side mode current measurement sense accuracy values
Comparator Update Speed			82		μs	When set to the 7-bit averaging speed
			328		μs	When set to the 9-bit averaging speed
CS2 Reverse Current Comparator Threshold Accuracy		–8.5	–3	+3	mV	Triggers SR_RC_FAULT flag SR_RC_FAULT_LIMIT set to –3 mV
		–11.5	–6	0	mV	SR_RC_FAULT_LIMIT set to –6 mV
		–14	–9	–3	mV	SR_RC_FAULT_LIMIT set to –9 mV
		–17	–12	–6	mV	SR_RC_FAULT_LIMIT set to –12 mV
		–21	–15	–9	mV	SR_RC_FAULT_LIMIT set to –15 mV
		–24	–18	–12	mV	SR_RC_FAULT_LIMIT set to –18 mV
		–27	–21	–15	mV	SR_RC_FAULT_LIMIT set to –21 mV
		–30	–24	–18	mV	SR_RC_FAULT_LIMIT set to –24 mV
Propagation Delay			110	150	ns	Debounce time = 40 ns
RTD TEMPERATURE SENSE PIN						
Input Voltage Range	V _{IN}	0		1.6	V	Voltage from RTD to AGND
Source Current		44.6	46	47.3	μA	Register 0xFE2D = 0xE6, factory default setting
		38.6	40	42	μA	Register 0xFE2D = 0xB0
		28.6	30	31.8	μA	Register 0xFE2D = 0x80
		18.6	20	21.6	μA	Register 0xFE2D = 0x40
	9.1	10	11	μA	Register 0xFE2D = 0x00	
RTD ADC						
Valid Input Voltage Range		0		1.6	V	
ADC Clock Frequency			1.56		MHz	
Register Update Rate			10		ms	
Measurement Resolution			12		Bits	

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
Measurement Accuracy		-0.3 -4.8 -2 -80		+0.45 +7.2 +2 +80	% FSR mV % FSR mV	2% to 20% of the input voltage range 0% to 100% of the input voltage range
OTP Digital Comparator Threshold Accuracy		-0.9 -14.4 -0.5 -8		+0.25 +4 +1.1 +17.6	% FSR mV % FSR mV	Triggers OT_FAULT flag T = 85°C with 100 kΩ 16.5 kΩ T = 100°C with 100 kΩ 16.5 kΩ
Comparator Update Speed Temperature Readings According to Internal Linearization Scheme			10		ms °C °C	Source current is set to 46 μA (Register 0xFE2D = 0xE6); NTC R25 = 100 kΩ (1%); beta = 4250 (1%); R _{EXT} = 16.5 kΩ (1%) 25°C to 100°C 100°C to 125°C
PG/ALT (OPEN-DRAIN) PIN Output Low Level	V _{OL}			0.4	V	Sink current = 10 mA
CTRL PIN Input Low Level Input High Level Leakage Current	V _{IL} V _{IH}			0.4 V _{DD} - 0.8 1.0	V V μA	
SYNI/FLGI PINS Input Low Level Input High Level Synchronization Range % of Internal Clock Period SYNI Positive Pulse Width SYNI Negative Pulse Width SYNI Period Drift Leakage Current	V _{IL} V _{IH} t _{SYNC}			0.4 V _{DD} - 0.8 90 360 360 280 1.0	V V % ns ns ns μA	External clock applied on SYNI/FLGI pin External clock applied on SYNI/FLGI pin Period drift between two consecutive external clocks
SDA, SCL PINS Input Voltage Low Input Voltage High Output Voltage Low Leakage Current	V _{IL} V _{IH} V _{OL}			0.8 V _{DD} - 0.8 0.4 -5 +5	V V V μA	Sink current = 3 mA
SERIAL BUS TIMING Clock Operating Frequency Glitch Immunity Bus Free Time Start Setup Time Start Hold Time Stop Setup Time SDA Setup Time SDA Hold Time SCL Low Timeout SCL Low Time SCL High Time SCL Low Extend Time SCL, SDA Rise Time SCL, SDA Fall Time	t _{BUF} t _{SU,STA} t _{HD,STA} t _{SU,STO} t _{SU,DAT} t _{HD,DAT} t _{TIMEOUT} t _{LOW} t _{HIGH} t _{LOW,SEXT} t _R t _F	10 1.3 0.6 0.6 0.6 100 125 300 25 0.6 0.6 25 20 20	100	400 50 35 25 300 300	kHz ns μs μs μs μs ns ns ns ms μs μs ms ns ns	See Figure 2 Between stop and start conditions Repeated start condition setup time Hold time after (repeated) start condition; after this period, the first clock is generated For readback For write

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
EEPROM						
EEPROM Update Time				40	ms	Time from the update command to completion of the EEPROM update
Reliability						
Endurance ²		10,000			Cycles	T _J = 85°C
		1000			Cycles	T _J = 125°C
Data Retention ³		20			Years	T _J = 85°C
		15			Years	T _J = 125°C

¹ CS3 is an alternative output current reading that is calculated by the CS1 reading (representing input current), duty cycle, and main transformer turn ratio.

² Endurance is qualified as per JEDEC Standard 22, Method A117, and is measured at -40°C, +25°C, +85°C, and +125°C.

³ Retention lifetime equivalent at junction temperature as per JEDEC Standard 22, Method A117.

Timing Diagram

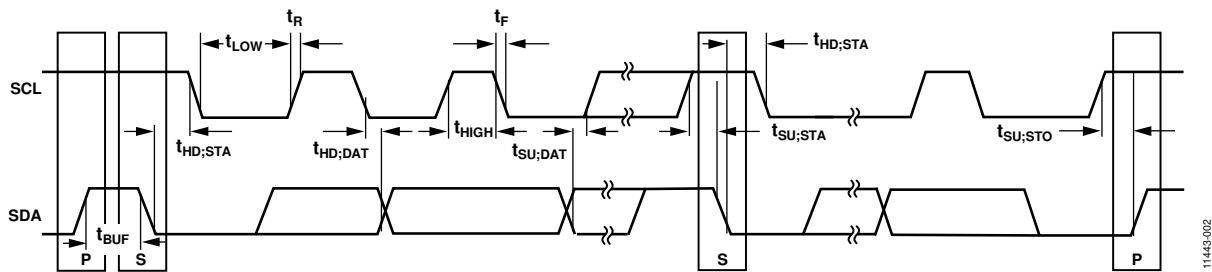


Figure 2. Serial Bus Timing Diagram

11443-002

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Rating
Supply Voltage (Continuous) V_{DD} to AGND	4.2 V
Digital Pins (OUTA, OUTB, OUTC, OUTD, SR1, SR2, PG/ALT, SDA, SCL) to AGND	-0.3 V to $V_{DD} + 0.3$ V
PG/ALT, SDA, SCL to AGND	-0.3 V to +3.9 V
$VS-$, $VS+$, VF, OVP, RTD, ADD, CS1, CS2+, CS2- to AGND	-0.3 V to $V_{DD} + 0.3$ V
SYNI/FLGI, CTRL to AGND	-0.3 V to $V_{DD} + 0.3$ V
Operating Temperature Range (T_A)	-40°C to +125°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature	150°C
Peak Solder Reflow Temperature	
SnPb Assemblies (10 sec to 30 sec)	240°C
RoHS-Compliant Assemblies (20 sec to 40 sec)	260°C
ESD Charged Device Model	1.25 kV
ESD Human Body Model	5.0 kV

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE

θ_{JA} is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 3. Thermal Resistance

Package Type	θ_{JA}	θ_{JC}	Unit
24-Lead LFCSP	36.26	1.51	°C/W

SOLDERING

It is important to follow the correct guidelines when laying out the printed circuit board (PCB) footprint for the ADP1051 and for soldering the part onto the PCB. For detailed information about these guidelines, see the [AN-772 Application Note, A Design and Manufacturing Guide for the Lead Frame Chip Scale Package \(LFCSP\)](#).

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

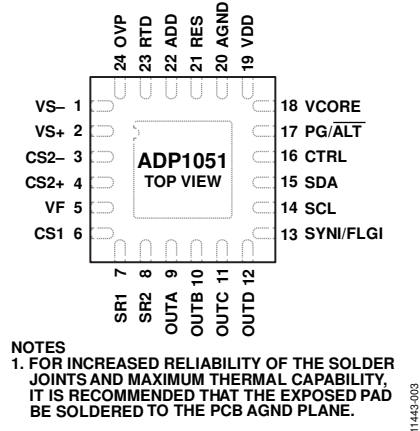


Figure 3. Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	VS-	Inverting Voltage Sense Input. This is the connection for the ground line of the power rail. Provide a low ohmic connection to AGND. To allow for trimming, it is recommended that the resistor divider on this input have a tolerance specification of $\leq 0.5\%$.
2	VS+	Noninverting Voltage Sense Input. This signal is referred to VS-. To allow for trimming, it is recommended that the resistor divider on this input have a tolerance specification of $\leq 0.5\%$.
3	CS2-	Inverting Differential Current Sense Input. For best operation, use a nominal voltage of 1.12 V. When using low-side current sensing, place a 4.99 k Ω level shifting resistor between the sense resistor and this pin. When using high-side current sensing in a 12 V application, place a 5.62 k Ω resistor between the sense resistor and this pin. When using high-side current sensing, apply the formula $R = (V_{OUT} - 1.12 V)/1.915 \text{ mA}$. A 0.1% resistor must be used to connect this circuit. If this pin is not used, connect it to AGND and set the CS2 current sense to high-side current sense mode (Register 0xFE19[7] = 1 binary).
4	CS2+	Noninverting Differential Current Sense Input. For best operation, use a nominal voltage of 1.12 V. When using low-side current sensing, place a 4.99 k Ω level shifting resistor between the sense resistor and this pin. When using high-side current sensing in a 12 V application, place a 5.62 k Ω resistor between the sense resistor and this pin. When using high-side current sensing, apply the formula $R = (V_{OUT} - 1.12 V)/1.915 \text{ mA}$. A 0.1% resistor must be used to connect this circuit. If this pin is not used, connect it to AGND and set the CS2 current sense to high-side current sense mode (Register 0xFE19[7] = 1 binary).
5	VF	Three optional functions can be implemented with this pin: feedforward, primary side input voltage sensing, and input voltage UVLO protection. The pin is connected upstream of the output inductor through a resistor divider network. The nominal voltage at this pin should be 1 V. This signal is referred to AGND.
6	CS1	Primary Side Current Sense Input. This pin is connected to the primary side current sensing ADC and to the cycle-by-cycle current-limit comparator. This signal is referred to AGND. The resistors on this input must have a tolerance specification of $\leq 0.5\%$ to allow for trimming. Connect this pin to AGND if not in use.
7	SR1	PWM Logic Output Drive. This pin can be disabled when not in use. This signal is referred to AGND.
8	SR2	PWM Logic Output Drive. This pin can be disabled when not in use. This signal is referred to AGND.
9	OUTA	PWM Logic Output Drive. This pin can be disabled when not in use. This signal is referred to AGND.
10	OUTB	PWM Logic Output Drive. This pin can be disabled when not in use. This signal is referred to AGND.
11	OUTC	PWM Logic Output Drive. This pin can be disabled when not in use. This signal is referred to AGND. This pin can also be programmed as a synchronization signal output (SYNO).
12	OUTD	PWM Logic Output Drive. This pin can be disabled when not in use. This signal is referred to AGND. This pin can also be programmed as a synchronization signal output (SYNO).
13	SYNI/FLGI	Synchronization Signal Input (SYNI)/External Signal Input to Generate a Flag Condition (FLGI). Connect this pin to AGND if not in use.
14	SCL	I ² C/PMBus Serial Clock Input and Output (Open Drain). This signal is referred to AGND.
15	SDA	I ² C/PMBus Serial Data Input and Output (Open Drain). This signal is referred to AGND.
16	CTRL	PMBus Control Signal. It is recommended that a 1 nF capacitor be connected from the CTRL pin to AGND for noise debounce and decoupling. This signal is referred to AGND.

Pin No.	Mnemonic	Description
17	PG/ $\overline{\text{ALT}}$	Power Good Output (Open Drain). Connect this pin to VDD through a pull-up resistor (typically 2.2 k Ω). This signal is referred to AGND. This pin is also used as an SMBus $\overline{\text{ALERT}}$ signal. (For information about the SMBus specification, see the PMBUS Features section.)
18	VCORE	Output of 2.6 V Regulator. Connect a decoupling capacitor of at least 330 nF from this pin to AGND, as close as possible to the ADP1051, minimizing the PCB trace length. It is recommended that this pin not be used as a reference or to generate other logic levels using resistive dividers.
19	VDD	Positive Supply Input. Voltage of 3.0 V to 3.6 V. This signal is referred to AGND. Connect a 2.2 μF decoupling capacitor from this pin to the AGND, as close as possible to the ADP1051, minimizing the PCB trace length.
20	AGND	Common Analog Ground. The internal analog circuitry ground and digital circuitry ground is star connected to this pin through bonding wires.
21	RES	Resistor Input. This pin sets up the internal reference for the internal PLL frequency. Connect a 10 k Ω resistor ($\pm 0.1\%$) from this pin to AGND. This signal is referred to AGND.
22	ADD	Address Select Input. This pin is used to program the I ² C/PMBus address. Connect a resistor from ADD to AGND. This signal is referred to AGND.
23	RTD	Thermistor Input. Place a thermistor (R25 = 100 k Ω (1%), beta = 4250 (1%)) in parallel with a 16.5 k Ω (1%) resistor and a 1 nF filtering capacitor. This pin is referred to AGND. Connect this pin to AGND if not in use.
24	OVP EP	Overvoltage Protection. This signal is used as redundant overvoltage protection. This signal is referred to AGND. Exposed Pad. The ADP1051 has an exposed thermal pad on the underside of the package. For increased reliability of the solder joints and maximum thermal capability, it is recommended that the exposed pad be soldered to the PCB AGND plane.

TYPICAL PERFORMANCE CHARACTERISTICS

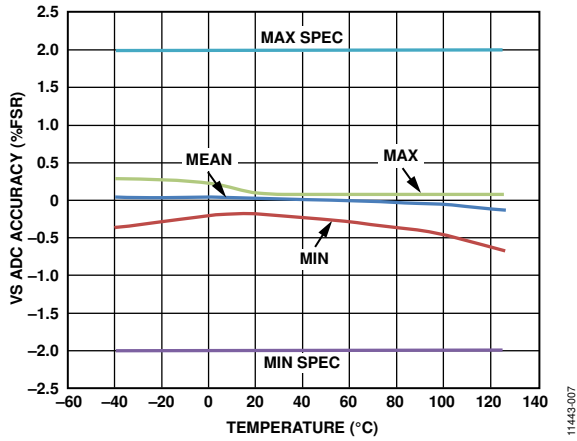


Figure 4. VS ADC Accuracy vs. Temperature (From 10% to 90% of FSR)

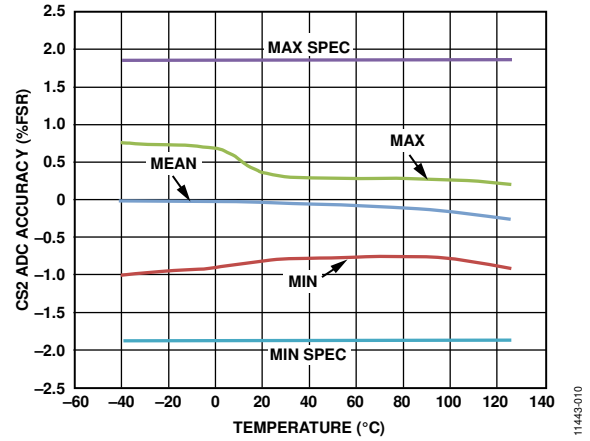


Figure 7. CS2 ADC Accuracy vs. Temperature (From 0 mV to 120 mV)

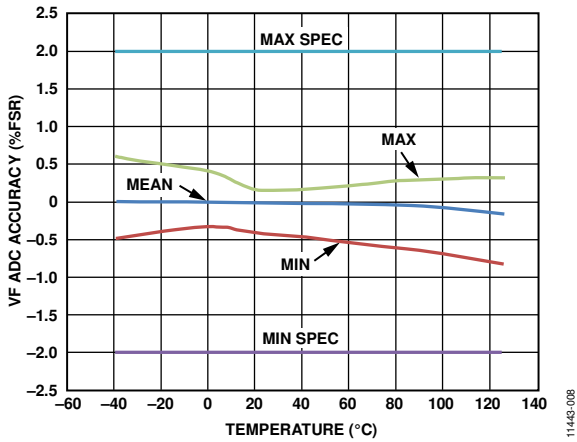


Figure 5. VF ADC Accuracy vs. Temperature (From 10% to 90% of FSR)

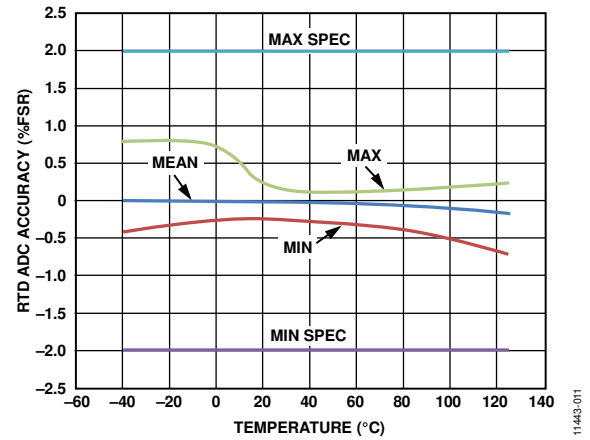


Figure 8. RTD ADC Accuracy vs. Temperature (From 10% to 90% of FSR)

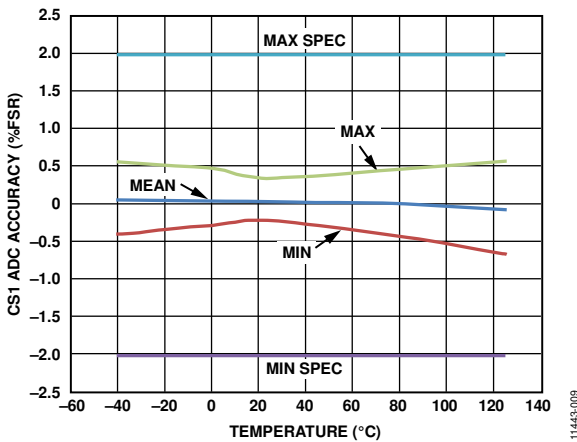


Figure 6. CS1 ADC Accuracy vs. Temperature (From 10% to 90% of FSR)

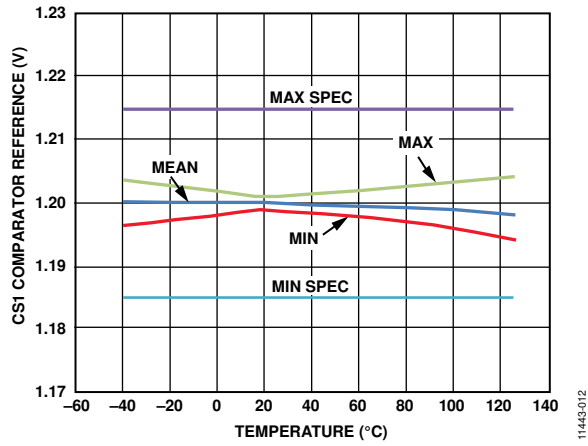


Figure 9. CS1 OCP Comparator Reference vs. Temperature (1.2 V Reference)

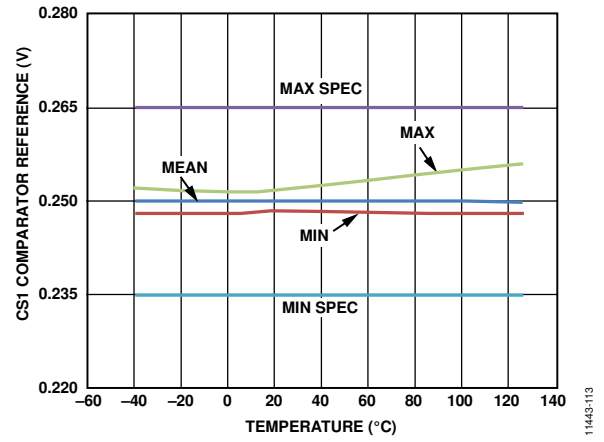


Figure 10. CS1 OCP Comparator Reference vs. Temperature (0.25 V Reference)

THEORY OF OPERATION

The **ADP1051** is designed as a flexible, easy to use, digital power supply controller. The **ADP1051** integrates the typical functions that are needed to control a power supply, such as

- Output voltage sense and feedback
- Voltage feedforward control
- Digital loop filter compensation
- PWM generation
- Current, voltage, and temperature sense
- Housekeeping and I²C/PMBus interface
- Calibration and trimming

The main function of controlling the output voltage is performed through use of the feedback ADCs, the digital loop compensator, and the digital PWM engine.

The feedback ADCs feature a patented multipath architecture, with a high speed, low resolution (fast and coarse) ADC and a low speed, high resolution (slow and accurate) ADC. The ADC outputs are combined to form a high speed and high resolution feedback path. Loop compensation is implemented using the digital compensator. This proportional, integral, derivative (PID) compensator is implemented in the digital domain to allow easy programming of filter characteristics, which is of great value in customizing and debugging designs. The PWM engine generates

up to six programmable PWM outputs for control of primary side FET drivers and synchronous rectification FET drivers. This programmability allows many generic and specific switching power supply topologies to be realized.

Conventional power supply housekeeping features, such as input voltage sense, output voltage sense, primary side current sense and secondary side current sense, are included. An extensive set of protections is offered, including overvoltage protection (OVP), overcurrent protection (OCP), overtemperature protection (OTP), undervoltage protection (UVP), and SR reverse current protection (RCP).

All of these features are programmable through the I²C/PMBus digital bus interface. This interface is also used for calibrations. Other information, such as input current, output current, and fault flags, is also available through this digital bus interface.

The internal EEPROM can store all programmed values and allows standalone control without a microcontroller. A free, downloadable GUI is available that provides all the necessary software to program the **ADP1051**. To obtain the latest GUI software and a user guide, visit <http://www.analog.com/digitalpower>.

The **ADP1051** operates from a single 3.3 V power supply and is specified from -40°C to $+125^{\circ}\text{C}$.

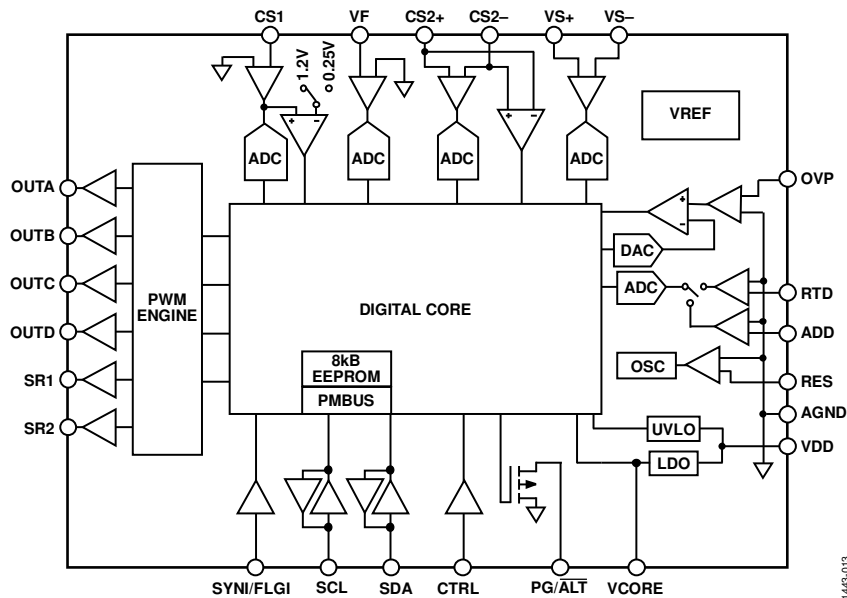


Figure 11. Functional Block Diagram

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PWM OUTPUTS (OUTA, OUTB, OUTC, OUTD, SR1, AND SR2)

The PWM outputs are used for control of the primary side drivers and the synchronous rectifier drivers. They can be used for several topologies, such as hard-switched full bridge, zero-voltage-switched full bridge, phase shifted full bridge, half bridge, push pull, two-switch forward, active clamp forward, interleaved buck, and others. Delays between rising and falling edges can be individually programmed. Special care must be taken to avoid shootthrough and cross conduction. It is recommended that the ADP1051 GUI software be used to program these outputs. Figure 12 shows an example configuration to drive a zero-voltage-switched full bridge topology with synchronous rectification. The QA, QB, QC, QD, QSR1, and QSR2 switches are driven separately by the PWM outputs (OUTA, OUTB, OUTC, OUTD, SR1, and SR2). Figure 13 shows an example of PWM settings for the power stage shown in Figure 12.

The PWM and SRx outputs are all synchronized with each other. Therefore, when reprogramming more than one of these outputs, it is important to first update all of the registers and then latch the information into the shadow registers at one time. During the reprogramming operation, the outputs are temporarily disabled. To ensure that new PWM timings and the switching frequency setting are programmed simultaneously, a special instruction is sent to the ADP1051 by setting Register 0xFE61[2:1] (the GO commands). It is recommended that the PWM outputs not in use be disabled via Register 0xFE53[5:0].

See the PWM Outputs Timing Registers section for additional information about the PWM timings.

SYNCHRONOUS RECTIFICATION

SR1 and SR2 are recommended for use as the PWM control signals when synchronous rectification is in use. These PWM signals can be configured much like the other PWM outputs.

An optional soft start can be applied to the synchronous rectifier (SR) PWM outputs. The SR soft start can be programmed using Register 0xFE08[4:0].

When the SR soft start is disabled (Register 0xFE08[1:0] = 00), the SR signals are immediately turned on to their modulated PWM duty cycle values.

When the SR soft start is enabled (Register 0xFE08[1:0] = 11), the SR1 and SR2 rising edges move left from the $t_{rx} + t_{MODU_LIMIT}$ position to the $t_{rx} + t_{MODULATION}$ position in steps that are set in Register 0xFE08[3:2]. t_{rx} represents the rising edge timing of SR1 (t_{rS}) and the rising edge timing of SR2 (t_{rR}) (see Figure 68); t_{MODU_LIMIT} represents the modulation limit defined in Register 0xFE3C (see Figure 67); $t_{MODULATION}$ represents the real-time modulation value. The SR soft start is still applicable even if the SR1 and SR2 are not programmed to be modulated. When the SR soft start is enabled, the SR1 and SR2 rising edges move left from the $t_{rx} + t_{MODU_LIMIT}$ position to the t_{rx} position in steps that are set in Register 0xFE08[3:2].

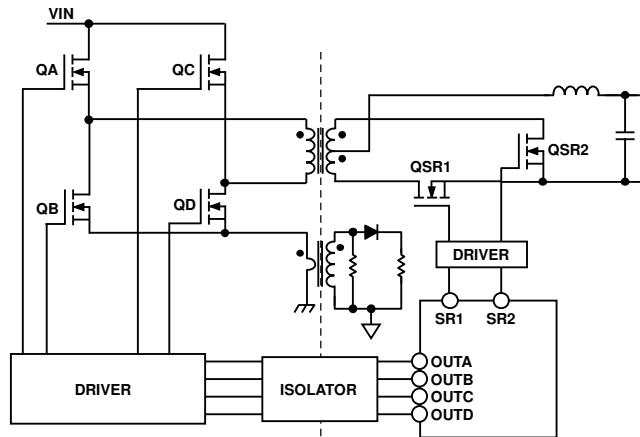


Figure 12. PWM Assignment for Zero-Voltage-Switched Full Bridge Topology with Synchronous Rectification

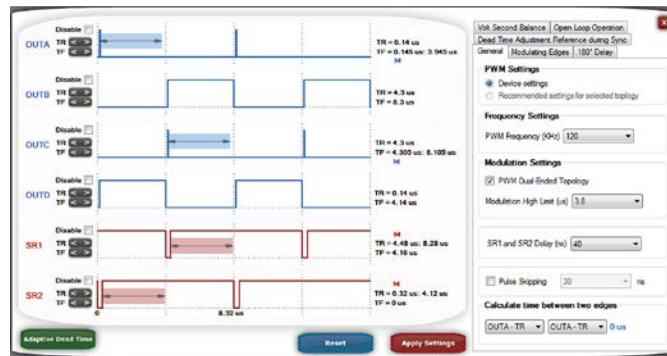


Figure 13. PWM Settings for Zero-Voltage-Switched Full Bridge Topology with Synchronous Rectification Using the ADP1051 GUI

The advantage of the SR soft start is that it minimizes the output voltage undershoot that occurs when the SR FETs are turned on without a soft start. The advantage of turning the SRx signals completely on immediately is that they can help minimize the voltage transient caused during a load step.

Using Register 0xFE08[4], the SR soft start can be programmed to occur only once (the first time that the SRx signals are enabled) or every time that the SRx signals are enabled (for example, when the system enters or exits deep light load mode).

When programming the ADP1051 to use the SR soft start, ensure the correct operation of this function by setting the falling edge of SR1 (t_{F5}) to a lower value than the rising edge of SR1 (t_{R5}) and setting the falling edge of SR2 (t_{F6}) to a lower value than the rising edge of SR2 (t_{R6}). During the SR soft start, the rising edges of SRx move gradually from the right side (the $t_{R6} + t_{MODU_LIMIT}$ position) to the left side to increase the duty cycle.

The ADP1051 is well suited for dc-to-dc converters in isolated topologies. Every time a PWM signal crosses the isolation barrier, a propagation delay is added because of the isolating components. Using Register 0xFE3A[5:0], an adjustable delay (0 ns to 315 ns in steps of 5 ns) can be programmed to move both SR1 and SR2 later in time to compensate for the added propagation delay. In this way, all the PWM edges can be aligned (see Figure 68).

PWM MODULATION LIMIT AND 180° PHASE SHIFT

The modulation limit register (Register 0xFE3C) can be programmed to apply a maximum modulation limit to any PWM signal, thus limiting the modulation range of any PWM output. If modulation is enabled, the maximum modulation limit is applied to all PWM outputs collectively. This limit, t_{MODU_LIMIT} , is the maximum time variation for the modulated edges from the default timing, following the configured modulation direction (see Figure 14). There is no setting for the minimum duty cycle limit. Therefore, the user must set the rising edges and falling edges based on the case with the least modulation.

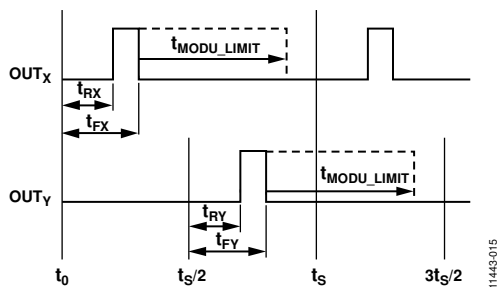


Figure 14. Setting Modulation Limits

Each least significant bit (LSB) in Register 0xFE3C corresponds to a different time step size, depending on the switching frequency (see Table 152). If the ADP1051 is to control a dual-ended topology (such as full bridge, half bridge, or push pull), enable the dual-ended topology mode using Register 0xFE13[6]. Then the modulation limit in each half cycle is one half of the modulation value programmed by Register 0xFE3C.

The modulated edges cannot go beyond one switching cycle. To extend the modulation range for some applications, the 180° phase shift can be enabled, using Register 0xFE3B[5:0]. When the 180° phase shift is disabled, the rising edge timing and the falling edge timing are referred to the start of the switching cycle (see t_{R6} and t_{F6} in Figure 14). When the 180° phase shift is enabled, the rising edge timing and the falling edge timing are referred to half of the switching cycle (see t_{R7} and t_{F7} in Figure 14, which are referred to $t_s/2$). Therefore, when the 180° phase shift is disabled, the edges are always located between t_0 and t_s . When the 180° phase shift is enabled, the edges are located between $t_s/2$ and $3t_s/2$.

The 180° phase shift function can be used to extend the maximum duty cycle in a multiphase, interleaved converter. Figure 15 shows a dual-phase, interleaved buck converter. The OUTC and OUTD PWM outputs can be programmed as a 180° phase shift with the OUTA and OUTB PWM outputs.

The phase shedding function can be used for light load efficiency improvement. See the Light Load Mode and Deep Light Load Mode section for more information.

The ADP1051 GUI is recommended for evaluating this feature.

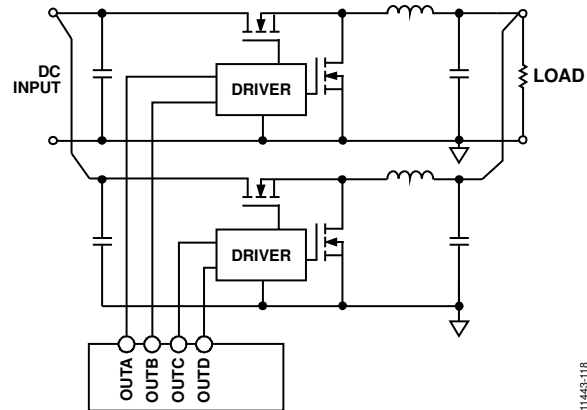


Figure 15. Dual-Phase Interleaved Buck Converter Controlled by the ADP1051

ADAPTIVE DEAD TIME COMPENSATION (ADTC)

The ADTC registers (Register 0xFE5A to Register 0xFE60 and Register 0xFE66) allow the dead time between the PWM edges to be adapted on the fly. The ADP1051 uses the ADTC function only when the CS1 current value (which represents the input current) falls below the ADTC threshold (programmed in Register 0xFE5A). The ADP1051 GUI allows the user to easily program the dead time values, and it is recommended that the GUI be used for this purpose.

Before the ADTC is configured, its threshold must be programmed. Each individual PWM rising and falling edge (t_{R6} and t_{F6}) can then be programmed (Register 0xFE5B to Register 0xFE60) to have a specific dead time offset at a CS1 current of 0 A.

This offset can be positive or negative and is relative to the nominal edge position. When the CS1 current is between 0 A and the ADTC threshold, the amount of dead time is linearly adjusted in steps of 5 ns.

The averaging period of the CS1 current and the speed of the dead time adjustment can also be programmed in Register 0xFE66 to accommodate faster or slower adjustment.

For example, if the ADTC threshold is set to 0.8 A, t_{R1} has a nominal rising edge of 100 ns. If the ADTC offset setting for t_{R1} is 100 ns at a CS1 current of 0 A, t_{R1} moves to 200 ns when the CS1 current is 0 A and to 150 ns when the CS1 current is 0.4 A. Similarly, the ADTC can be applied in the negative direction.

LIGHT LOAD MODE AND DEEP LIGHT LOAD MODE

To facilitate efficiency over the load range, the following three operation modes can be configured in the [ADP1051](#), according to the programmed CS2 current thresholds:

Normal mode. In normal mode, the SR PWM outputs are in complement with the primary PWM outputs.

Light load mode. The SR PWM outputs still work, but they are in phase with the primary PWMs.

Deep light load mode. All PWM outputs can be disabled.

Figure 16 shows the operation timing of a hard-switched full bridge converter. When the CS2 current (output current) drops across the light load mode threshold programmed by Register 0xFE19[3:0], the SR1 and SR2 PWM signals switch from complementary mode (normal mode) to in-phase mode (light load mode), as shown in Figure 16.

To achieve normal operation of light load mode, keep in mind the following:

In a hard-switched full bridge topology having the same power stage shown in Figure 12, if QA to QD are driven by OUTA to OUTD separately, program the SR1 output in complement with OUTB and OUTC in normal mode, and program the SR2 output in complement with OUTA and OUTD, as shown in Figure 16. In this case, the OUTA to OUTD outputs are all modulated.

In a zero-voltage-switched full bridge topology having the same power stage shown in Figure 12 and the PWM settings shown in Figure 13, SR1 is in complement with OUTC and SR2 is in complement with OUTA in normal mode. In light load mode, SR1 is in phase with OUTA, and SR2 is in phase with OUTC.

If the hard-switched full bridge, half bridge, and push pull topologies are used and the primary switches are controlled by OUTA and OUTB only, SR1 is in complement with OUTB, and SR2 is in complement with OUTA in normal mode. Then, in the light load mode, SR1 is in phase with OUTA, and SR2 is in phase with OUTB.

When the CS2 current drops across the deep light load mode threshold programmed by Register 0xFE1B[3:0], all PWM channels can be disabled by Register 0xFE1C[5:0]. This allows the [ADP1051](#) to be used in interleaved topologies, incorporating the automatic phase shedding function in light load mode.

In both light load mode and deep light load mode, the CS2 averaging speed for the threshold can be set from 41 μ s to 328 μ s in four discrete steps, using Register 0xFE1E[5:4]. The hysteresis can be set by Register 0xFE1E[3:2].

The light load mode digital compensator is also used during light load mode and deep light load mode.

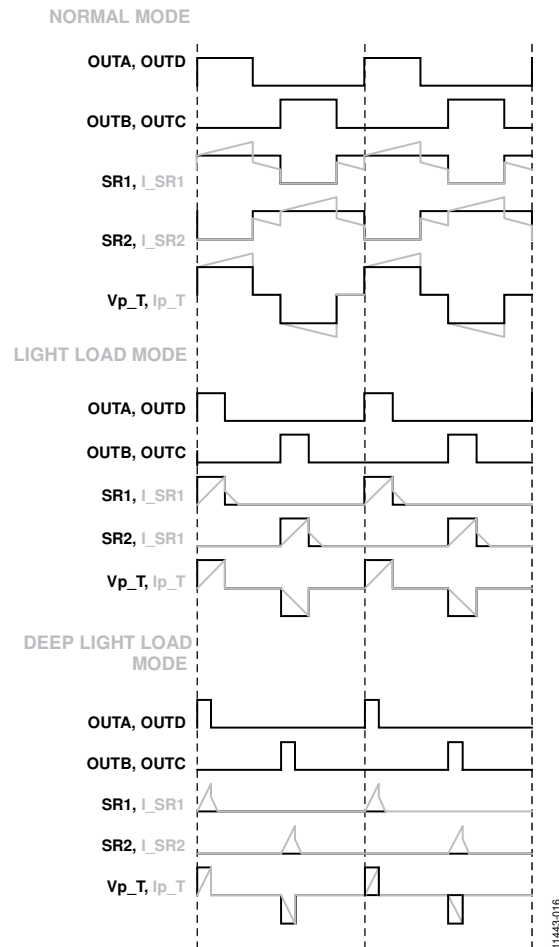


Figure 16. Light Load Mode and Deep Light Load Mode

FREQUENCY SYNCHRONIZATION

The frequency synchronizing function of the [ADP1051](#) includes the synchronization input (SYNI) as a slave device and the synchronization output (SYNO, using the OUTC or OUTD pin) as a master device.

Synchronization as a Slave Device

The [ADP1051](#) can be programmed to take the SYNI/FLGI pin signal as the reference to synchronize the internal programmed PWM clock with an external clock.

The frequency capture range requirement is for the period of the external clock that is applied at the SYNI pin to be 90% to 110% of the period of the internal programmed PWM clock. The minimum pulse width of the SYNI signal is 360 ns. From the rising edge of the SYNI signal to the start of the internal clock cycle, there is a 760 ns propagation delay. Additional delay time is programmed, using Register 0xFE11, to realize interleaving control with different controllers.

To achieve a smooth synchronization transition between asynchronous operation and synchronous operation, there is a phase capture range bit for synchronization in Register 0xFE12[6] for capturing

the phase of the external clock signal. The ADP1051 detects the phase shift between the external clock signal and the internal clock signal when synchronization is enabled. When the phase shift falls within the phase capture range, synchronization begins.

The ADP1051 synchronizes to the external clock frequency as follows:

1. The synchronization function is enabled by Register 0xFE12[3] and Register 0xFE12[0], and the ADP1051 starts to detect the period of the external clock signal applied at the SYNI/FLGI pin.
2. If all the periods of the consecutive 64 most recent cycles of the external clocks fall within 90% to 110% of the internal switching clock period, the ADP1051 uses the latest current cycle as the synchronization reference, and the period of the external clock is identified. This interval is t_2 or t_4 , as shown in Figure 17. Otherwise, the ADP1051 discards this cycle and looks for the next cycle (frequency capture mode).
3. After the external clock period is determined, the ADP1051 detects the phase shift between the external clock (plus the delay time set by Register 0xFE11) and the internal PWM signal. If the phase shift is within the phase capture range, the internal and external clocks are synchronized (phase capture mode).
4. At this point, the PWM clock is synchronized with the external clock. Cycle-by-cycle synchronization starts.
5. If the external clock signal is lost at any time, or if the period exceeds the minimum limit (89% of the internal programmed frequency) or the maximum limit (114% of the internal programmed frequency), the ADP1051 takes the last valid external clock signal as the synchronization reference source.

At the same time, the phase shift between the synchronization reference and the internal clock is detected. When the phase shift falls within the phase capture range, the PWM clock returns to the internal clock set by the internal oscillator.

This interval is t_1 or t_3 , as shown in Figure 17.

This is the first synchronization unlock condition, called Synchronization Unlocked Mode 1, in which the switching frequency is out of range (range is 89% to approximately 114% of the internal programmed frequency).

6. If the period of the external SYNI signal changes significantly (for example, if the period difference between contiguous cycles exceeds 280 ns), the ADP1051 takes the last valid external clock signal as the synchronization reference source. At the same time, the phase shift between the synchronization reference and the internal clock is detected. When the phase shift falls within the phase capture range, the PWM clock returns to the internal clock set by the internal oscillator. This is the second synchronization unlock condition, called Synchronization Unlocked Mode 2, in which the phase shift exceeds 280 ns.

Figure 17 shows the synchronous operation diagram. The internal frequency, f_{SW_INT} , is the internal free-running frequency of the ADP1051. Before the synchronization is locked, the ADP1051 runs at f_{SW_INT} . The external frequency, f_{SW_EXT} , is the frequency of the external clock that the ADP1051 needs to synchronize. After synchronization is locked, the ADP1051 runs at f_{SW_EXT} .

The ADP1051 does not allow the switching frequency to run across the boundaries of 97.5 kHz, 195.5 kHz, or 390.5 kHz on the fly. Ensure that the external clock does not run across these boundaries. Otherwise, the internal switching frequency cannot be set within $\pm 10\%$ of these boundaries.

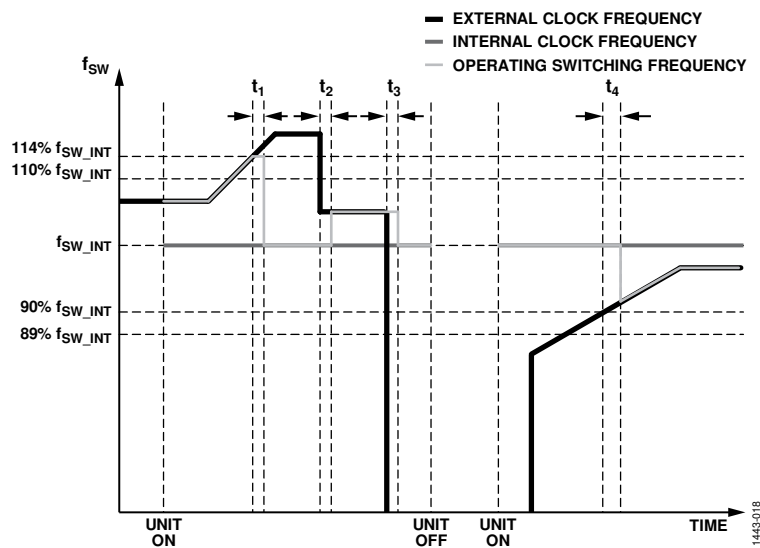
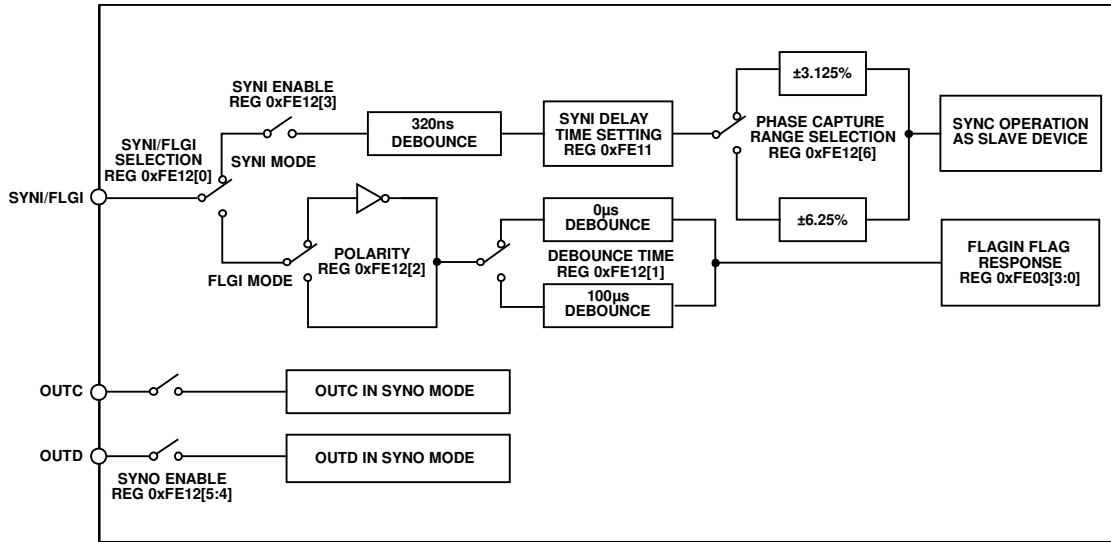
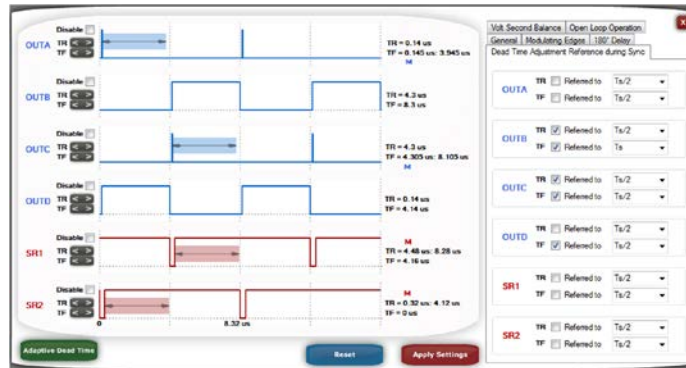


Figure 17. Synchronization Operation



11443-017

Figure 18. Synchronization Configuration



11443-019

Figure 19. Edge Adjustment Reference During Synchronization

To ensure a constant dead time before and after synchronization, Register 0xFE6D to Register 0xFE6F can be set for edge adjustment referred to $t_s/2$ or t_s . For example, the falling edge of OUTA (t_{F1}) is referred to the $\frac{1}{2} \times t_s$ position, which means that the time difference between t_{F1} and $\frac{1}{2} \times t_s$ is a constant during synchronization transition. Figure 19 shows an example of the edge adjustment reference settings in a full bridge topology.

Synchronization as a Master Device

Register 0xFE12[5:4] can be used to program the synchronization output (SYNO) function, in which the OUTC pin (Pin 11) or the OUTD pin (Pin 12) generates a synchronization reference clock output. When Bit 4 is set, OUTC generates a 640 ns pulse width clock signal that represents the internal switching frequency. When Bit 5 is set, OUTD generates a 640 ns pulse width clock signal that also represents the internal switching frequency.

To compensate the propagation delays in the synchronization scheme of the ADP1051, the synchronization output signal has a 760 ns lead time before the start of the internal switching cycle.

The synchronization output signal is always available when VDD is applied. The VDD_OV fault is the only fault condition that suspends the synchronization output signal.

OUTPUT VOLTAGE SENSE AND ADJUSTMENT

The output voltage sense and adjustment function is used for control, monitoring, and undervoltage protection of the remote output voltage. VS- (Pin 1) and VS+ (Pin 2) are fully differential inputs. The voltage sense point can be calibrated digitally to remove any errors due to external components. This calibration can be performed in the production environment, and the settings can be stored in the EEPROM of the ADP1051 (see the Power Supply Calibration and Trim section for more information).

For voltage monitoring, the READ_VOUT output voltage command (Register 0x8B) is updated every 10 ms. The ADP1051 stores every ADC sample for 10 ms and then calculates the average value at the end of the 10 ms period. Therefore, if Register 0x8B is read at least every 10 ms, a true average value is obtained. The voltage information is available through the I²C/PMBus interface.

The control loop of the ADP1051 features a patented multipath architecture. The output voltage is converted simultaneously by two ADCs: a high accuracy ADC and a high speed ADC. The complete signal is reconstructed and processed in the digital compensator to provide a high performance and cost competitive solution.

Voltage Feedback Sensing (VS+, VS– Pins)

The VS sense point on the power rail requires an external resistor divider (R1 and R2 in Figure 20) to bring the nominal differential mode signal to 1 V between the VS+ and VS– pins (see Figure 20). This external resistor divider is necessary because the VS ADC input range of the ADP1051 is 0 V to 1.6 V. When R1 and R2 are known, the VOUT_SCALE_LOOP parameter can be calculated using the following equation:

$$VOUT_SCALE_LOOP = R2 / (R1 + R2)$$

In a 12 V system with resistor dividers of 11 kΩ and 1 kΩ, the VOUT_SCALE_LOOP can be calculated as follows:

$$VOUT_SCALE_LOOP = 1\text{ k}\Omega / (11\text{ k}\Omega + 1\text{ k}\Omega) = 0.08333$$

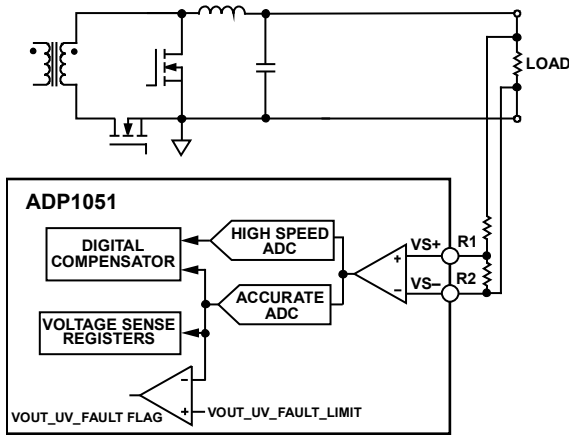


Figure 20. Voltage Sense Configuration

Voltage Sense ADCs

Two kinds of sigma-delta (Σ-Δ) ADCs are used in the ADP1051 feedback loop, as follows:

- Low frequency (LF) ADC, running at 1.56 MHz
- High frequency (HF) ADC, running at 25 MHz

The Σ-Δ ADCs have a resolution of one bit and operate differently from traditional flash ADCs. The equivalent resolution that is obtained depends on how long the output bit stream of the Σ-Δ ADC is filtered.

The Σ-Δ ADCs also differ from Nyquist rate ADCs in that the quantization noise is not uniform across the frequency spectrum. At lower frequencies, the noise decreases. At higher frequencies, the noise increases (see Figure 21).

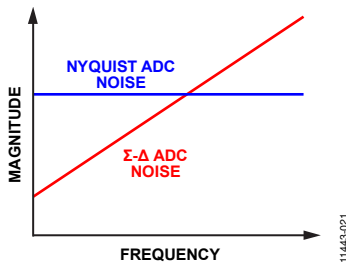


Figure 21. ADC Noise Performance

The low frequency ADC runs at approximately 1.56 MHz. For a specified bandwidth, the equivalent resolution is calculated as

$$\ln(1.56\text{ MHz}/BW) / \ln(2) = N\text{ bits}$$

For example, at a bandwidth of 95 Hz, the equivalent resolution/noise is

$$\ln(1.56\text{ MHz}/95\text{ Hz}) / \ln(2) = 14\text{ bits}$$

At a bandwidth of 1.5 kHz, the equivalent resolution/noise is

$$\ln(1.56\text{ MHz}/1.5\text{ kHz}) / \ln(2) = 10\text{ bits}$$

The high frequency ADC has a 25 MHz clock. It is comb filtered and outputs at the switching frequency into the digital compensator. See Table 5 for equivalent resolution at selected sampling frequencies.

Table 5. Equivalent Resolutions for High Frequency ADC at Selected Switching Frequencies

f _{sw} (kHz)	High Frequency ADC Resolution (Bits)
49 to 87	9
97.5 to 184	8
195.5 to 379	7
390.5 to 625	6

The high frequency ADC has a range of ±25 mV. Using a base switching frequency of 97.5 kHz at an 8-bit HF ADC resolution, the quantization noise is 0.195 mV (1 LSB = 2 × 25 mV/2⁸ = 0.195 mV). When the switching frequency increases to 195.5 kHz at a 7-bit HF ADC resolution, the quantization noise is 0.391 mV (1 LSB = 2 × 25 mV/2⁷ = 0.391 mV). Increasing the switching frequency to 390.5 kHz increases the quantization noise to 0.781 mV (1 LSB = 2 × 25 mV/2⁶ = 0.781 mV).

Output Voltage Adjustment Commands

In the ADP1051, the voltage data for commanding or reading the output voltage or related parameters is in linear data format. The linear format exponent is fixed at –10 decimal (see the VOUT_MODE command, Register 0x20, in Table 21).

The following three basic commands are used for setting the output voltage:

- VOUT_COMMAND command (Register 0x21, Table 22)
- VOUT_MARGIN_HIGH command (Register 0x25, Table 26)
- VOUT_MARGIN_LOW command (Register 0x26, Table 27)

One of these three values is selected by the OPERATION command (Register 0x01, Table 13).

The VOUT_MAX command (Register 0x24, Table 25) sets an upper limit on the output voltage that the ADP1051 can command, regardless of any other commands or combinations.

During output voltage adjustment, use the VOUT_TRANSITION_RATE command (Register 0x27, Table 28) to set the rate (in mV/μs) at which the VS± pins change voltage.

If the digital compensator output remains unchanged and the VF voltage changes to 200% of its original value (still smaller than 1.6 V), the modulation of the OUTx edges that are configured for modulation is divided by 2 (see Figure 23). Register 0xFE3D[3:2] is used to program the optional input voltage feedforward function.

The VF pin also has a low speed, high resolution Σ - Δ ADC. The ADC has an update rate of 800 Hz with 11-bit resolution. The ADC output value is stored in Register 0xFEAC and converted to the READ_VIN command (Register 0x88). This value provides information for the input voltage monitoring and flag functions.

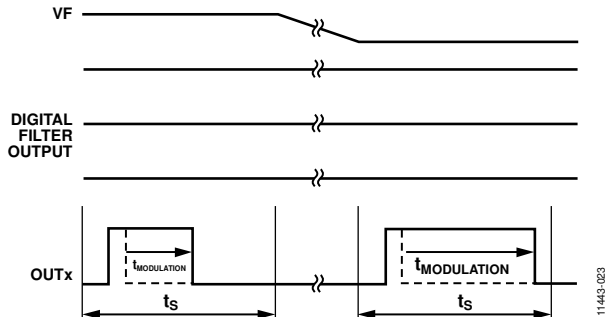


Figure 23. Closed-Loop Input Voltage Feedforward Changes Modulation Values

OPEN-LOOP INPUT VOLTAGE FEEDFORWARD OPERATION

The ADP1051 can run in open-loop input voltage feedforward operation mode. In this mode, the input voltage is sensed as the feedforward signal for generation of the PWM outputs.

As shown in Figure 24, the digital compensator output is modified by a programmable modulation reference. The VF value, which represents the input voltage, is fed into the feedforward ADC to divide the modulation reference. The result of this division is then fed into the PWM engine. The duty cycle value is in inverse proportion to the input voltage.

Using the following equations:

$$D = \frac{V_{IN_NOM}}{V_{IN}} \times (t_{REF} \times f_{SW})$$

and

$$V_{OUT} = \frac{V_{IN} \times D}{n}$$

the output voltage can be derived by

$$V_{OUT} = \frac{V_{IN_NOM} \times (t_{REF} \times f_{SW})}{n}$$

where:

D is the duty cycle value.

V_{IN_NOM} is the nominal input voltage.

V_{IN} is the input voltage.

t_{REF} is the modulation reference, which is set by Register 0xFE63 and Register 0xFE64.

f_{SW} is the switching frequency.

V_{OUT} is the output voltage.

n is the turn ratio of the main transformer.

In the equation to derive V_{OUT} , the input voltage, V_{IN} , is cancelled out. Therefore, the output voltage does not change when the input voltage changes.

Register 0xFE63 and Register 0xFE64 set the modulation reference, based on the target output voltage and the nominal input voltage at which the VF pin voltage is 1 V (see Figure 24).

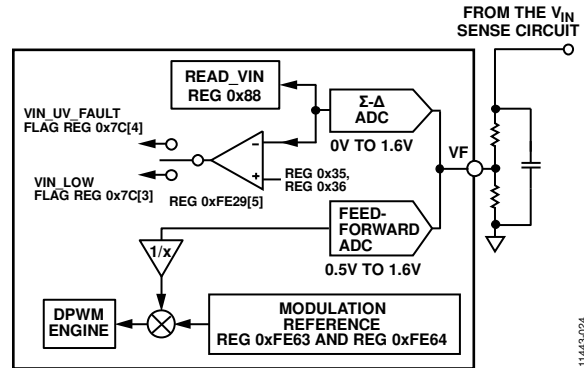


Figure 24. Open-Loop Feedforward Operation

The PWM settings of open-loop input voltage feedforward operation are similar to those of general closed-loop operation. The falling edge timings, rising edge timings, and modulation are set in the same manner as for closed-loop operation, by using Register 0xFE3E to Register 0xFE52. Register 0xFE09[4:3] sets the soft start speed of the modulation edges. Register 0xFE3D[6] enables open-loop feedforward operation. Register 0xFE3D[7] is used to enable the soft start procedure of open-loop feedforward operation.

The flag settings of open-loop feedforward operation are also similar to those of general closed-loop operation.

Because the output voltage is not regulated in the same manner as closed-loop operation, some settings, such as the V_{OUT} setting, the digital compensator settings, and the constant current mode setting, are not functional. Other settings can be programmed in a manner that is similar to general closed-loop operation.

OPEN-LOOP OPERATION

The ADP1051 can also run in open-loop operation mode. In this mode, the rising edges and falling edges of the PWM outputs are fixed during normal operation. Therefore, the output voltage varies with the input voltage. The topologies include full bridge, half bridge, and push pull converters.

The PWM settings of open-loop operation are different from those of general closed-loop operation.

1. Set the rising edge timings and falling edge timings by using Register 0xFE3E to Register 0xFE4F. Typically, a duty cycle setting of ~50% is recommended for ease of zero-voltage-switching operation. A phase shift function of 180° is preferred to guarantee balanced PWM outputs.
2. Program Register 0xFE3C to a value of 0x00, which sets the modulation limit to 0 μ s.
3. Apply negative modulation to the falling edges of all PWM outputs, OUTA to OUTD (or just one pair of them), for soft start. The soft start of SR1 and SR2 is not recommended.
4. Write 111111 binary to Register 0xFE67[5:0] to set all PWM channels to follow open-loop operation. Set Register 0xFE09[7] to enable the soft start procedure. The soft start speed is specified by Register 0xFE09[4:3].
5. Always set Register 0xFE09[2] = 1. The soft start ramp time is determined by $t_{F2} - t_{R2}$.

Because the output voltage is not regulated, some of the settings, such as the V_{OUT} setting, digital compensator settings, and constant current control, are not functional. Other settings can be programmed to be similar to those of general closed-loop operation.

CURRENT SENSE

The ADP1051 has two current sense inputs: CS1 (Pin 6) and CS2-/CS2+ (Pin 3 and Pin 4, respectively). These inputs sense, protect, and control the primary side input current and the secondary side output current. They can be calibrated to reduce errors due to the external components.

CS1 Operation (CS1 Pin)

Current Sense 1 (CS1) is typically used for the monitoring and protection of the primary side current, which is commonly sensed using a current transformer (CT). The input signal at the CS1 pin is fed into an ADC for current monitoring. The range of the ADC is 0 V to 1.60 V. The input signal is also fed into an analog comparator for cycle-by-cycle current limiting and I_{IN} overcurrent fast protection, with a reference of 0.25 V or 1.2 V set by Register 0xFE1B[6].

The typical configuration for the CS1 current sense is shown in Figure 25.

The CS1 ADC is used to measure the average value of the primary side current. The ADC samples at a frequency of 1.56 MHz and reports a CS1 reading (12 bits) in the READ_IIN command (Register 0x89), with an asynchronously averaged rate of 10 ms, 52 ms, 105 ms, or 210 ms set by Register 0xFE65[1:0].

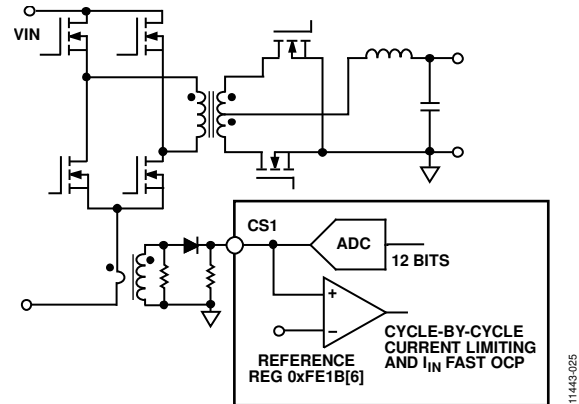


Figure 25. Current Sense 1 (CS1) Operation

Various I_{IN} overcurrent fast fault limits and response actions can be set for CS1. These are described in the Current Sense and Limit Setting Registers section.

CS2 Operation (CS2-, CS2+ Pins)

Current Sense 2 (CS2) is typically used for the monitoring and protection of the output current. The full-scale range of the CS2 ADC is 120 mV. The differential inputs are fed into an ADC through a pair of external resistors that provide the necessary level shifting. The CS2+ and CS2- device pins are regulated to approximately 1.12 V by internal current sources.

Depending on the configuration of the current sense resistor, the ADP1051 must be programmed in low-side mode or high-side mode, using Register 0xFE19[7]. Typical configurations are shown in Figure 26 and Figure 27.

When using low-side current sensing, as shown in Figure 26, the current sources are 225 μ A. Therefore, the required resistor value is $1.12 \text{ V} / 225 \mu\text{A} = 4.98 \text{ k}\Omega$, and 4.99 k Ω resistors are preferred.

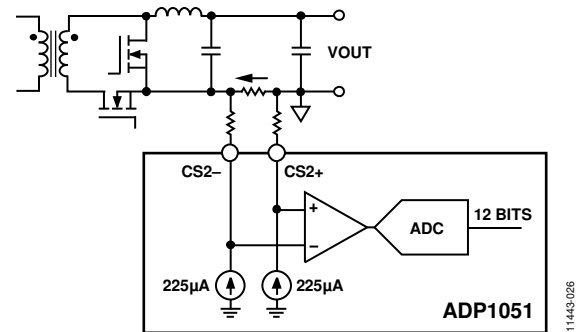


Figure 26. CS2 Low-Side Resistive Current Sense

When using high-side current sensing, as shown in Figure 27, the current sources are 1.915 mA. Therefore, the required resistor value is $(V_{OUT} - 1.12 \text{ V})/1.915 \text{ mA}$. If $V_{OUT} = 12 \text{ V}$, 5.62 kΩ resistors are required.

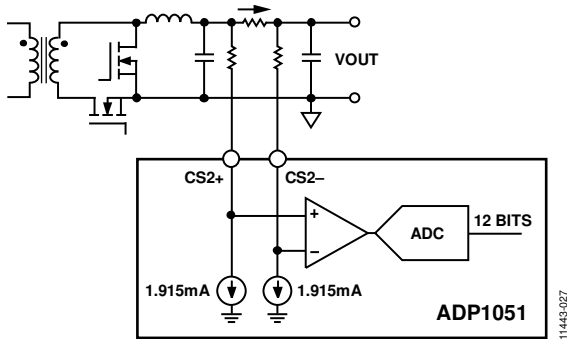


Figure 27. CS2 High-Side Resistive Current Sense

The ADC samples at a frequency of 1.56 MHz, and the reading is averaged in an asynchronous fashion. This reading is used to determine actions on faults, such as the IOUT OC fault, with an average rate of 82 μs (seven bits) or 328 μs (nine bits), which is set by Register 0xFE1B[4]. The ADP1051 also reports an output current reading in the READ_IOUT command (Register 0x8C), with an average rate of 10 ms, 52 ms, 105 ms, or 210 ms, as set by Register 0xFE65[1:0].

Various limits and response actions can be set for CS2, such as the IOUT_OC_FAULT_LIMIT command (Register 0x46) and the IOUT_OC_FAULT_RESPONSE (Register 0x47) command. These

limits and responses are described in the PMBUS Command Set and Current Sense and Limit Setting Registers section.

SOFT START AND SHUTDOWN

On/Off Control

The OPERATION command (Register 0x01) and the ON_OFF_CONFIG command (Register 0x02) control the power-on and power-off behavior of the ADP1051. The OPERATION command turns the ADP1051 on and off in conjunction with input from the CTRL pin (Pin 16). The combination of the CTRL pin input and serial bus commands required to turn the ADP1051 on and off is configured by the ON_OFF_CONFIG command. When the ADP1051 is commanded to turn on, the power supply on (PSON) signal is enabled, and the ADP1051 follows the soft start procedure to begin the power conversion.

Soft Start

After VDD power-up and initialization, the PSON signal is enabled when the ADP1051 is commanded to turn on. The controller waits for a user specified turn-on delay (TON_DELAY, Register 0x60) before initiating this output voltage soft start ramp. The soft start is then performed by actively regulating the output voltage and digitally ramping up the target voltage to the commanded voltage setpoint. The rise time of the voltage ramp is programmed, using the TON_RISE command (Register 0x61), to minimize the inrush currents associated with the start-up voltage ramp. A nonzero pre-biased voltage results in a longer turn-on delay and shorter rise time.

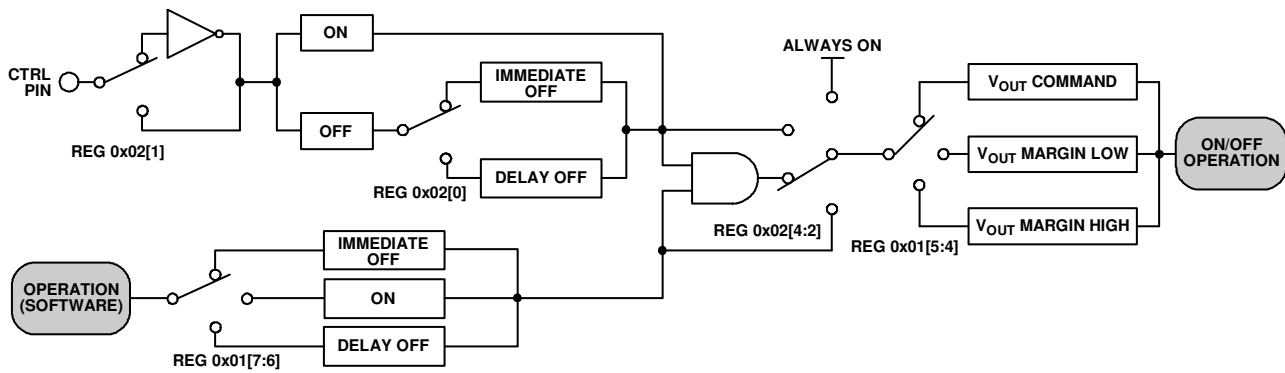


Figure 28. On/Off Control Diagram

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